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121-05 A/B

LOW SPECIFIC GRAVITY, LOW TEMPERATURE CURING, ELECTRICALLY CONDUCTIVE, EPOXY POTTING COMPOUND AND ADHESIVE

DESCRIPTION: 121-05 A/B is a two component, 100% solids, low specific gravity, low temperature curing, silver-filled, epoxy potting compound and adhesive. The 121-05 A/B is designed to be used for making electrical and mechanical attachments on electrical components and devices. 121-05 A/B can also be used as an electrically conductive potting compound and encapsulant. Unlike typical heat curing systems, this product always results in excellent conductivity and is less sensitive to handling and ambient conditions. The mix ratio can be varied to achieve full cure in thin section or in large mass without exotherming.

	<u>Part A</u>	<u>Part B</u>
Appearance:	Silver	Amber
Consistency:	Paste	Liquid
Mix Ratio (by weight)		
Thin section:	100	8.11
Thick section:	100	6.00
Pot Life:	----	> 24 hours

MIXING INSTRUCTIONS: Premix Part A in original container prior to combining. Add Part B to Part A and mix until uniform. **Note:** It is not unusual for crystallization of the Part A or Part B to occur. Warm to 40-45°C in a water bath to return the material to it's original viscosity. The crystallization does not effect the performance of the product in any way.

CURING INSTRUCTIONS: Best results are obtained when product is cured at one of the following schedules:

Thin section (small mass):	1 hour at 100°C or 4 hours at 80°C
Thick section (mass of <30 grams):	2 hours at 80°C

TYPICAL CURED PROPERTIES:

Volume Resistivity, max. (Ω-cm)	0.03
Glass Transition Temperature (°C)	150
Tensile Shear Strength, min. (psi)	1000
Solvent Resistance	Excellent
Solderable	No
Specific Gravity (100: 8.11):	2.51
(100: 6.00):	2.58

SHELF LIFE: (at room temp in unopened unmixed containers.) 1 year

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

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